

**●LGA-10B01 Power Dissipation**

Power dissipation data for the LGA-10B01 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

**1. Measurement Condition**

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40mmx40mm (1600mm<sup>2</sup> in one side)

1<sup>st</sup> Layer: Approx. 50% connect to lead 1/5/6/10

2<sup>nd</sup> Layer: Approx. 50% connect to lead 1/5/6/10

3<sup>rd</sup> Layer: Approx. 50% connect to lead 1/5/6/10

4<sup>th</sup> Layer: Approx. 50% connect to lead 1/5/6/10

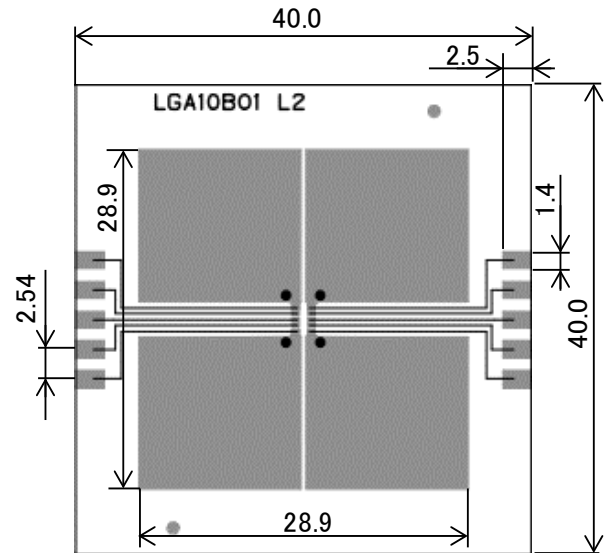
The copper area is divided into four block,  
one block is 12.5% of total.

Each terminal connects one copper block in the  
front and one in the back.

Material: Glass Epoxy (FR-4)

Thickness: 1.6mm

Through-hole: 4 x 0.8 Diameter



Evaluation Board (Unit: mm)

**2. Power Dissipation vs. Ambient temperature**

Board Mount ( Tjmax=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1200	83.33
105	240	

